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10/645,065	00.00.000			
10/645,065 08/21/2003		Kenichi Yokouchi	P/2699-30	6981
2352 7590	11/18/2005	EXAMINER		
	ABER GERB & SOFF	MACARTHUR, SYLVIA		
1180 AVENUE OF NEW YORK, NY			ART UNIT	PAPER NUMBER
,			1763	

DATE MAILED: 11/18/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

		Appl	Application No. Applicant(s)					
		10/6	45,065	YOKOUCHI ET AL.				
	Office Action Summary	Exar	niner	Art Unit				
		Sylvi	a R. MacArthur	1763				
- Period fo	- The MAILING DATE of this communic r Reply	ation appears o	on the cover sheet with the c	correspondence ad	dress			
A SHO WHIC - Exten after S - If NO - Failur Any re	DRTENED STATUTORY PERIOD FOR HEVER IS LONGER, FROM THE MA sions of time may be available under the provisions of SIX (6) MONTHS from the mailing date of this community period for reply is specified above, the maximum statue to reply within the set or extended period for months after department. See 37 CFR 1.704(b).	LING DATE C 37 CFR 1.136(a). In ication. tory period will apply II, by statute, cause t	F THIS COMMUNICATION no event, however, may a reply be tine and will expire SIX (6) MONTHS from the application to become ABANDONE	N. nely filed the mailing date of this co D (35 U.S.C. § 133).				
Status								
1)[🖂	Responsive to communication(s) filed	on 20 August	2005					
·	1)⊠ Responsive to communication(s) filed on <u>29 August 2005</u> . (a)□ This action is FINAL . 2b)⊠ This action is non-final.							
′=								
<i>,</i> —	closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Dispositio	on of Claims	·						
5)□ 6)⊠ 7)□	Claim(s) <u>1-60</u> is/are pending in the applant of the above claim(s) <u>9,10,12-16,2</u> Claim(s) is/are allowed. Claim(s) <u>1-8,11,17-19,22,23 and 25-3</u> Claim(s) is/are objected to. Claim(s) are subject to restriction	<u>0,21,24 and 3</u> <u>0</u> is/are rejecte	d.	consideration.				
	on Papers		·					
	The specification is objected to by the	Evaminar						
10)🛛 1	The drawing(s) filed on 22 August 2005 Applicant may not request that any objection Replacement drawing sheet(s) including the oath or declaration is objected to be	is/are: a)☐ a on to the drawin ne correction is r	g(s) be held in abeyance. See equired if the drawing(s) is ob	e 37 CFR 1.85(a). jected to. See 37 CF	FR 1.121(d).			
Priority u	nder 35 U.S.C. § 119							
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 								
Attachment	(s)							
2) Notice 3) Inform	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO lation Disclosure Statement(s) (PTO-1449 or PT No(s)/Mail Date <u>8/22/2003</u> .		4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ate)-152)			

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Election/Restrictions

1. Applicant's election of claims 1-8,11,17-19, 22, 23, and 25-30 in the reply filed on 8/29/2005 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)).

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 3. Claims 1-8, 11, 17-19, 22, 23, and 25-30 are rejected under 35 U.S.C. 102(b) as being anticipated by Miya Katsuhiko et al (JP 11-330031).

Katsuhiko et al teaches a substrate processor.

Regarding claim 1: A substrate processing apparatus that removes an unwanted material on a surface of a peripheral portion of a substrate through etching by supplying etching liquid to the surface of the peripheral portion, the apparatus comprising: an etching liquid supplying mechanism (48, 68) that supplies the etching liquid to the peripheral portion of the substrate; and an annular member (1,2) that has an inner periphery on or inside an outer periphery of the substrate and thereby defines a processing width to be processed by the etching liquid on the

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surface of the peripheral portion of the substrate.

Regarding claim 2: The substrate processing apparatus according to claim 1

wherein:

the annular member is placed in close proximity to the

surface of the peripheral portion of the substrate while

securing a certain gap such that allows the annular member to

come in contact with a liquid film of the etching liquid formed

on the surface of the peripheral portion, See Figs. 1, 2,5, and 6 of Katsuhiko et al.

Regarding claim 3:

The substrate processing apparatus according to Claim 1

further comprising:

substrate holding mechanism (base plate 60) that holds the substrate

from one surface side thereof,

wherein the annular member 4 is placed on the other surface

side of the substrate.

Regarding claim 4: The substrate processing apparatus according to Claim

1, wherein: the etching liquid is supplied to the peripheral portion

of the substrate from the etching liquid supplying mechanism

while the substrate is held rest. The apparatus of Katshiko et al is inherently capable of

supplying etching liquid while the substrate is not rotating. This is also seen as a process

limitation and is not given patentable weight.

Regarding claim 5: The substrate processing apparatus according to Claim

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1, wherein the substrate W is a substrate of a nearly circular shape;

the apparatus further comprises a substrate rotating

mechanism that rotates the substrate; and

the inner periphery of the annular member is of a circular

shape having an inside diameter equal to smaller than a

diameter of the substrate. See Figs. 1,2,5, and 6 of Katsuhiko et al.

Regarding claim 6: The substrate processing apparatus according to Claim

5, wherein: the etching liquid is supplied to the peripheral portion

of the substrate from the etching liquid supplying mechanism

while the substrate rotated by the substrate rotating

mechanism, see abstract.

Regarding claim 7: The substrate processing apparatus according to Claim

1 wherein:

the annular member 4,6 includes a substrate-opposing

surface that extends

outwards from the inner periphery and

opposes the surf ace of the peripheral portion of the substrate.

Regarding claim 8: The substrate processing apparatus according to Claim

wherein: the substrate-opposing surface is a plane nearly

parallel the surface of the peripheral portion of the

substrate, see Figs. 1,2,5, and 6.

Regarding claim 9: The substrate processing apparatus according to Claim

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wherein: the substrate-opposing surface is an inclined plane inclined to reduce an interval between the substrate-opposing surface and the substrate as heading toward the inner periphery, see Fig.6.

Regarding claim 10: The substrate processing apparatus according to Claim 7, wherein: an outer periphery of the substrate-opposing surface is located outside the outer periphery of the substrate, see Figs. 1,2,5, and 6.

Regarding claim 11: The substrate processing apparatus according to

Claim 7, wherein:

the annular member includes a projection that protrudes from the substrate-opposing surface toward the substrate and thereby limits the etching liquid heading toward an inside of the substrate, see Fig. 6.

Regarding claim 17: Claim 1, wherein:

the etching liquid supplying mechanism includes a nozzle 48 that supplies the etching liquid toward a surface of the substrate on an opposite side to a surface containing the surface of the peripheral portion.

Regarding claim 18: The substrate processing

Claim wherein: apparatus according

the nozzle supplies the etching

liquid toward a central portion of the surface on the opposite side, see Fig. 6.

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Regarding claim 19: The substrate processing apparatus according

claim 1, wherein: the annular member has an outer wall surface positioned

inside the outer periphery of the substrate, see Fig. 6.

Regarding claim 22: The substrate processing

Claim 1, wherein:

apparatus according to

the etching liquid supplying mechanism includes a

dispense port 47 through which the etching liquid is dispensed

direction perpendicular to a surface of the substrate

direction inclined toward an outside of the substrate.

Regarding claim 23: The substrate processing

Claim 1, wherein: apparatus according the annular member includes

an inner wall surface that in a direction to go away from

rises from the inner periphery surface of the substrate, see Fig. 6.

Regarding claim 25: The substrate processing apparatus according to claim 1, further

comprising a lid member (plate 40) that substantially clogs an internal space

of the annular member.

Regarding claim 26: The substrate processing apparatus according to claim 25 wherein;

the annular member includes an annular groove formed adjacently inside the inner

periphery, see Fig. 6.

Regarding claim 27: The substrate processing apparatus according to claim 1,

further comprising: a gas supplying mechanism that supplies an internal space

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the annular member with a gas, see Fig. 1

Regarding claim 28: The substrate processing

apparatus according to claim 27, wherein

the annular member includes an inner wall surface that

rises from the inner periphery in a direction to go away from

a surface of the substrate, and the gas supplied from the gas

supplying mechanism is supplied toward the

inner wall surface, see [0063].

Regarding claim 29: The substrate processing

apparatus according to claim 23,

the annular member includes a gas flowing path that

allows a communication between an internal space and an

external space of the annular member, see [0063].

Regarding claim 30: The substrate processing apparatus according to

claim 1 further comprising:

a protection liquid etching protection liquid toward a center of the substrate

an inner side of the annular member. supplying mechanism that supplies etching

protection liquid toward a center a center of the substrate at an inner side of the annular

member, see Fig. 1,2,5, and 6.

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4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Sylvia R. MacArthur whose telephone number is 571-272-1438. The examiner can normally be reached on M-F during the core hours of 9 a.m. and 3 p.m..

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Parviz Hassanzadeh can be reached on 571-272-1435. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Sylvia R MacArthur Patent Examiner Art Unit 1763

November 14, 2005